

Low-Voltage Synchronous Boost Converter

General Description

The MAX20471, MAX20472, and MAX20472B are high-efficiency low-voltage DC-DC converters that boost a 3.0V to 4.0V input supply to between 3.8V and 5.25V (factory-configurable) at 500mA or 1A. The boost converters achieve $\pm 1.5\%$ output error over load, line, and temperature range.

The devices feature a 2.2MHz (2.0MHz for MAX20472B) fixed-frequency PWM mode for better noise immunity and load-transient response, and a pulse-frequency modulation mode (skip) for increased efficiency during light-load operation. The 2.2MHz/2.0MHz frequency operation allows for the use of all ceramic capacitors and minimizes external components. The programmable spread-spectrum frequency modulation minimizes radiated electromagnetic emissions. Integrated low-R_{DSON} switches improve efficiency at heavy loads and make the layout a much simpler task with respect to discrete solutions.

Other features include True Shutdown™, soft-start, overcurrent, and overtemperature protections.

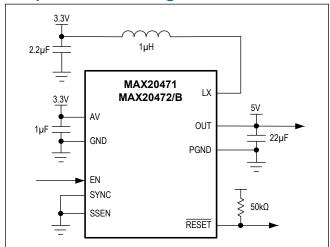
Applications

- · Automotive Point of Load
- Automotive CAN Transceivers

Benefits and Features

- Multiple Functions for Small Size
 - Synchronous Boost Converter
 - 3.8V to 5.25V Factory-Preset Output in 50mV Steps
 - · 500mA and 1A Options
 - · 3V to 4V Operating Supply Voltage
 - · True Output Shutdown
 - 2.2MHz Operation for the MAX20471/MAX20472
 - · 2.0MHz Operation for the MAX20472B
 - Open-Drain Reset Output Pin (RESET)
 - Spread-Spectrum Enable Pin (SSEN)
- High Precision
 - ±1.5% Output Voltage Accuracy
 - 93 ±2% UV Monitoring
 - 107 ±2% OV Monitoring
 - Good Load-Transient Performance
- Robust for the Automotive Environment
 - · Current-Mode, Forced-PWM, and Skip Operation
 - Overtemperature and Short-Circuit Protection
 - 12-Pin (3mm x 3mm) TDFN
 - 12-Pin (3mm x 3mm) SWTDFN
 - 8-Pin (0.150") SOIC (MAX20471 Only)
 - -40°C to +125°C Automotive Temperature Range

Simplified Block Diagram



True Shutdown is a trademark of Maxim Integrated Products, Inc.

Ordering Information appears at end of data sheet.

19-100163; Rev 16; 12/24

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Absolute Maximum Ratings

EN, SYNC to GND	0.3V to 6V	Continuous Po
AV to GND	0.3V to 6V	12-Pin TDFN
RESET to GND	0.3V to 6V	12-Pin SWT
OUT to PGND	0.3V to 6V	8-Pin SOIC (
SSEN to GND	0.3V to V _{AV} +0.3V	Operating Tem
LX to PGND (Note 1)	0.3V to V _{OUT} +0.3V	Junction Temp
GND to PGND	0.3V to 0.3V	Storage Tempe
Maximum Continuous RMS Current	2.5A	Soldering Tem
Output Short-Circuit Duration	Continuous	•

Continuous Power Dissipation (Note 2)	
12-Pin TDFN-EP (derate 24.4 mW/°C > 70	°C)1951mW
12-Pin SWTDFN-EP (derate 24.4 mW/°C >	> 70°C)1951mW
8-Pin SOIC (derate 7.8mW/°°C > +70°C)	623mW
Operating Temperature Range	40°C to +125°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Soldering Temperature (reflow)	+300°C

Note 1: Self-protected from transient voltages exceeding these limits in circuit under normal operation.

Note 2: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

12 TDFN

Package Code	TD1233+2C
Outline Number	<u>21-0664</u>
Land Pattern Number	90-0397
Thermal Resistance, Four-Layer Board:	
Junction to Ambient (θ _{JA})	41°C/W
Junction to Case (θ _{JC})	8.5°C/W

12 SWTDFN

Package Code	TD1233Y+2C			
Outline Number	<u>21-100176</u>			
Land Pattern Number	<u>90-100072</u>			
Thermal Resistance, Four-Layer Board:				
Junction to Ambient (θ _{JA})	41°C/W			
Junction to Case (θ _{JC})	8.5°C/W			

8 SOIC

Package Code	S8+2C			
Outline Number	<u>21-0041</u>			
Land Pattern Number	<u>90-0096</u>			
Thermal Resistance, Four-Layer Board:				
Junction to Ambient (θ _{JA})	128.4°C/W			
Junction to Case (θ_{JC})	36°C/W			

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Electrical Characteristics

 $(V_{AV} = 3.3V, EN = 3.3V, T_A = T_J = -40^{\circ}C$ to +125°C, unless otherwise noted., Typical values are at $T_A = +25^{\circ}C$ under normal conditions unless otherwise noted. (*Note 3*))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Supply Voltage Range	V _{IN}	(<u>Note 4</u>)	3		4.25	V	
UVLO	V _{UVLOR}	Rising	2.48	2.55	2.9	V	
UVLO	V _{UVLOF}	Falling	2.475			7 v	
Shutdown Supply Current	I _{SD}	EN = LOW		0.1	2	μA	
Supply Current	I _{IN}	EN = high, I _{OUT} = 0mA, SYNC low		130		μA	
PWM Switching	£	Internally Generated	2	2.2	2.4	N41.1-	
Frequency	fsw	Internally Generated, MAX20472B	2.0	2.12	- MHz		
Spread Spectrum	SS	SSEN high		±3		%	
OUT						•	
Voltage Accuracy	V _{OUT}	$I_{LOAD} = 0A \text{ to } I_{MAX,} 3V \le V_{AV} \le 4.25V$	-1.5		+1.5	%	
pMOS On-Resistance	R _{HS}	V _{AV} = 3.3V, I _{LX} = 0.18A		150		mΩ	
nMOS On-Resistance	R _{LS}	V _{AV} = 3.3V, I _{LX} = 0.18A		100		mΩ	
nMOS Current-Limit	I _{LIM1}	MAX20471	1.4	1.8	4		
Threshold	I _{LIM2}	MAX20472/MAX20472B	2.8	4.2	7	A	
pMOS Turn Off Threshold	I _{ZX}			50		mA	
LX Leakage Current	ILXLKG	V_{AV} = 6V, LX = PGND or OUT, T_A = 25°C		0.1		μA	
Maximum Duty Cycle	DC _{MAX}		90			%	
OUT Discharge Resistance	R _{DISCH}	V _{EN} = 0V (connected to OUT)		300		Ω	
SKIP Threshold	TH _{SKIP}	Percentage of nMOS current-limit threshold (MAX20471/MAX20472 only)		15		%	
Soft-Start Time	t _{SS}			1.9		ms	
THERMAL OVERLOAD			•				
Thermal Shutdown Temperature	T _{SHDN}	T _J rising		165		°C	
Hysteresis	T _{HYST}			15		°C	
RESET	•		•				
OV Threshold	OV _{ACC}	Rising, % of nominal output	105	107	109	%	
UV Threshold	UV _{ACC}	Falling, % of nominal output	91	93	95	%	
	t _{HOLD1}	Option 1 (default)		0.5			
Asthor Hald David	t _{HOLD2}	Option 2		3.7			
Active Hold Period	t _{HOLD3}	Option 3		7.4		ms	
	t _{HOLD4}	Option 4		14.8		1	
Delay Filter	tuvdel	10% below/above threshold		10		μs	
Output-High Leakage Current	I _{RLKG}	T _A = 25°C	-0.5	0.1	+0.5	μA	
Output Low Level	V _{ROL}	Sinking -2mA, 3V ≤ V _{AV} ≤ 4.25V			0.2	V	
	I NOL					1	

Electrical Characteristics (continued)

 $(V_{AV} = 3.3V, EN = 3.3V, T_A = T_J = -40^{\circ}C$ to +125°C, unless otherwise noted., Typical values are at $T_A = +25^{\circ}C$ under normal conditions unless otherwise noted. (*Note 3*))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS		
ENABLE AND SYNC INPUTS								
Input High Level	V _{IH}		1.5			V		
Input Low Level	V_{IL}				0.5	V		
Input Hysteresis	V _{HYST}			0.1		V		
EN Pulldown Current	I _{ENPD}	V _{AV} = 3.3V	0.5	1	2	μA		
SYNC Input Pulldown	R _{SYNCPD}	EN high		100		kΩ		
SYNC Input Frequency Range	fSYNC		1.7		2.6	MHz		

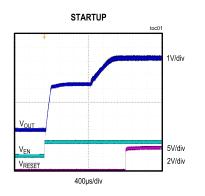
Note 3: All units are 100% production tested at +25°C. All temperature limits are guaranteed by design and characterization.

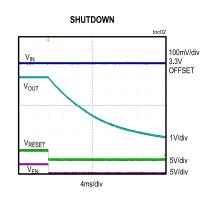
Note 4: FPWM operation is only guaranteed up to 4.0V supply voltage. Supply voltages higher than 4.0V will exhibit skip mode behavior even with SYNC = HIGH for FPWM operation.

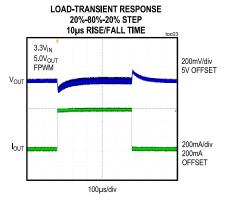
Low-Voltage Synchronous Boost Converter

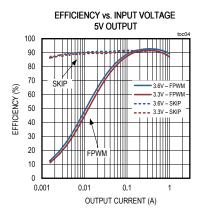
Typical Operating Characteristics

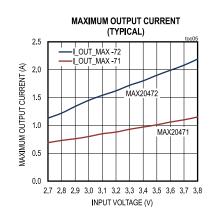
 $(AV_{VDD} = +3.3V, V_{DDIO} = +1.8V, V_{REFP} - V_{REFN} = V_{REF} = 2.5V;$ No Line-Frequency Rejection, Continuous-Conversion Mode, Internal Clock; $T_A = T_{MIN}$ to T_{MAX} unless otherwise noted.)

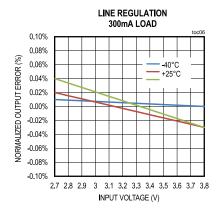






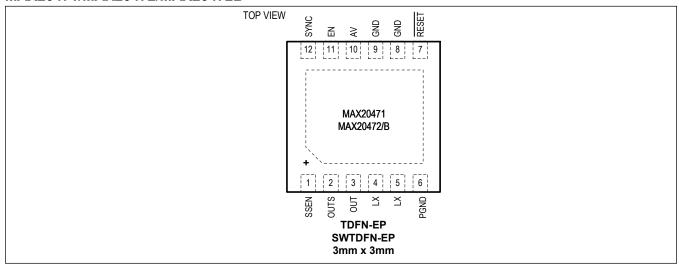




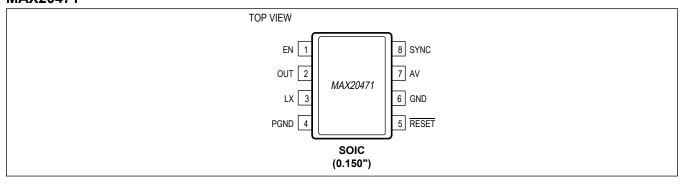


Pin Configurations

MAX20471/MAX20472/MAX20472B



MAX20471



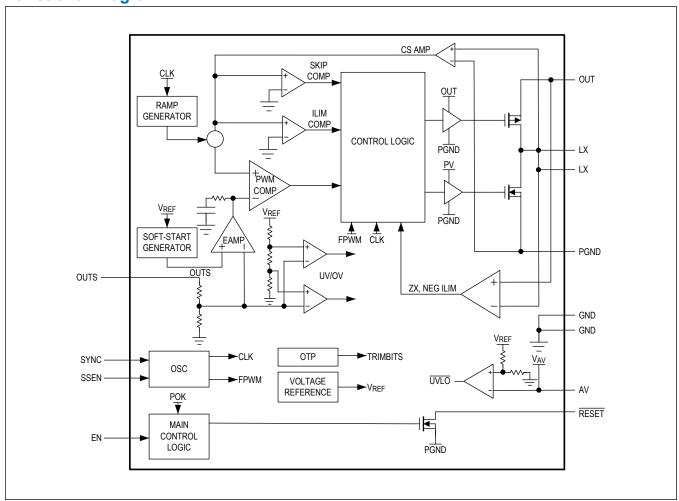
Pin Description

PI	IN					
MAX20471/ MAX20472/ MAX20472B	MAX20471	NAME	FUNCTION			
1	_	SSEN	Spread-Spectrum Enable. Connect to $V_{\mbox{AV}}$ to enable spread spectrum.			
2	_	OUTS	Output Voltage Feedback Pin. Connect this pin to the output capacitor.			
3	2	OUT	Output Voltage.			
4, 5	3	LX	Inductor Connection. Connect LX to the switched side of the inductor.			
6	4	PGND	Power Ground.			
7	5	RESET	Open-Drain RESET Output. To obtain a logic signal, pull up RESET with an external resistor.			
8	_	GND	Ground. Connect all ground pins to the EP.			
9	6	GIND	Analog Ground. Connect all ground pins to the EP.			
10	7	AV	Analog Power Input Supply. Connect a 1µF ceramic capacitor from V _{AV} to GND.			

Pin Description (continued)

P	IN				
MAX20471/ MAX20472/ MAX20472B	MAX20471	NAME	FUNCTION		
11	1	EN	Active-High Enable. Drive EN HIGH for normal operation.		
12	8	SYNC	SYNC Input. Connect SYNC to GND or leave unconnected to enable skip-mode operation under light loads. Connect SYNC to V_{AV} or an external clock to enable fixed-frequency, forced-PWM-mode operation.		
-	_	EP	Exposed Pad. Connect the exposed pad to ground. Connecting the exposed pad to ground does not remove the requirement for proper ground connections to PGND. The exposed pad is attached with epoxy to the substrate of the die, making it an excellent path to remove heat from the IC.		

Functional Diagram



Detailed Description

The MAX20471, MAX20472, and MAX20472B are high-efficiency, low-voltage 500mA and 1A synchronous DC-DC boost converter ICs that boost the 3.0V to 4.0V input supply to a fixed output voltage between 3.8V and 5.25V. The boost converters have True Shutdown, so the output voltage will be 0V when off. The ICs achieve ±1.5% output error over load, line, and temperature ranges.

The ICs feature either a 2.2MHz (MAX20471/MAX20472) or a 2.0MHz (MAX20472B) fixed-frequency FPWM mode for better noise immunity and load-transient response, as well as pulse-frequency operation that allows the use of all-ceramic capacitors, thus minimizing external components. The programmable spread-spectrum frequency modulation minimizes radiated electromagnetic emissions. The spread modulation is factory set to pseudorandom. Integrated low $R_{DS(ON)}$ switches improve efficiency at heavy loads, which makes the layout a much simpler task with respect to discrete solutions.

The ICs contain high-accuracy, factory-set OV/UV thresholds for each output mapped to the RESET pin. There are diagnostics on the RESET and OUT pins to guarantee high reliability and fail-safe operation. In light-load applications, a logic input (SYNC) allows the ICs to operate either in skip mode for reduced current consumption, or fixed-frequency FPWM mode to eliminate frequency variation and help minimize EMI.

Enable Input (EN)

The EN input activates the ICs' channels from their low-power shutdown state. EN has an input threshold of 1.0V (typ), with hysteresis of 100mV (typ). When EN goes high, the associated output voltage ramps up with the programmed soft-start time.

RESET Output

The device features individual open-drain, active-low reset <u>outputs</u> for each output that asserts low when the corresponding output voltage is outside of the UV/OV window. RESET remains asserted for a fixed timeout period after the output rises up to its regulated voltage. The fixed timeout <u>period</u> is selectable between 0.5ms, 3.7ms, 7.4ms, or 14.8ms. To obtain a logic signal, place a resistor pullup between RESET pins to the system I/O voltage.

Internal Oscillator

The device has a spread-spectrum oscillator that varies the internal operating frequency up by $\pm 3\%$ relative to the internally generated typical operating frequency. This function does not apply to externally applied oscillation frequency. The spread frequency generated is pseudorandom with a repeat rate well below the audio band. Spread spectrum on MAX20471ASAA is enabled as an internal setting. Contact customer support for more details.

Synchronization (SYNC)

The ICs have an on-chip oscillator that provides a 2.2 MHz/2.0 MHz switching frequency. Depending on the condition of the SYNC pin for the MAX20471/MAX20472, two operation modes exist. If SYNC is unconnected or at GND and the load current is below the skip-mode current threshold, the ICs will operate in a highly efficient pulse-skipping mode. If the current is above the threshold, the ICs automatically change to FPWM mode. If SYNC is at V_{AV} or has a frequency applied to it, the ICs will always operate in FPWM mode. The ICs can be switched during operation between FPWM or skip mode by pulling SYNC up to V_{AV} or down to GND.

For the MAX20472B, the SYNC pin operates differently. If the SYNC is unconnected or at GND for the MAX20472B the device will remain in pulse-skipping operation regardless of load current. If SYNC pin for the MAX20472B is at V_{AV} or has a frequency applied to it, the device will always operate in FPWM mode.

Soft-Start

The IC includes a fixed soft-start of 1.9ms. Soft-start time limits start-up inrush current by forcing the output voltage to ramp up towards its regulation point.

Current-Limit/Short-Circuit Protection

The device features current limit that protects the device against short-circuit and overload conditions at the output. In the

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event of a short-circuit or overload condition, the low-side MOSFET remains on until the inductor current reaches the low-side MOSFET's current-limit threshold. The converter then turns on the high-side MOSFET to allow the inductor current to ramp down. Once the inductor current crosses below the high-side MOSFET current-limit threshold, the converter turns on the low-side MOSFET again. This cycle repeats until the short or overload condition is removed.

PWM/SKIP Modes

The device features an input (SYNC) that puts the converter either in SKIP mode for forced PWM mode of operation. See <u>Pin Descriptions</u> for mode detail. In PWM mode of operation, the converter switches at a constant frequency with variable on-time. In SKIP mode of operation, the converter's switching frequency is load dependent until the output load reaches a certain threshold. At higher load current, the switching frequency does not change and the operating mode is similar to the PWM mode. SKIP mode helps improve efficiency in light-load applications by allowing the converter to turn on the high-side switch only when the output voltage falls below a set threshold. As such, the converter does not switch MOSFETs on and off as often as is the case in the PWM mode. Consequently, the gate charge and switching losses are much lower in SKIP mode.

Overtemperature Protection

Thermal overload protection limits the total power dissipation in the MAX20471, MAX20472, and MAX20472B. When the junction temperature exceeds 165°C (typ), an internal thermal sensor shuts down the internal bias regulator and the step-down controller, allowing the IC to cool. The thermal sensor turns on the IC again after the junction temperature cools by 15°C.

Boost Converter Short Protection

The boost has protection against startup into short and also protection against short/overload after startup.

Charge Mode

After the boost is enabled, the internal pMOS rectifier is configured as a 2A (typ) current source. This mode of operation is referred to as charge mode and is used to charge the output to within 600mV of the input. Under normal circumstances, charge mode is successful and the boost begins soft-start to programmed V_{OUT}. If the output is shorted or overloaded, charge mode will be unable to charge the output to within 600mV of the input. If charge mode lasts for more than 1.9ms, the boost shuts off and automatically attempts to restart after 120ms. This automatic restart is called hiccup mode, and it continues indefinitely until the short is removed. Disabling and then reenabling the boost overrides the 120ms timer and the boost will retry immediately.

Some variants of the MAX2047x family feature reduced charge-mode current capabilities as described in previous sections. When these variants are enabled, the current source is much smaller than the 2A (typ). This requires that the load current not exceed 200mA in order for the part to charge the output up to within 600mV of the input, as well as for it to support a load that may exist at startup. Additionally, C_{OUT} is limited to $40\mu F$ maximum for these variants. These variants can be found in the <u>Ordering Information</u> table by the percentage of full charge mode current they are capable of supporting.

Short or Overload after Soft-Start

After soft-start is complete, the boost continues monitoring to ensure that the output is always greater than the 600mV input. If a short or overload condition pulls the output below the 600mV input, the boost stops switching and re-enters the charge-mode configuration. If the output continues to fall below 3.125V, independent of the input voltage, the boost shuts off and enters hiccup mode, as described above.

Applications Information

Input Capacitor

The input filter capacitor reduces peak currents drawn from the power source and reduces noise and voltage ripple on the input caused by the circuit's switching. A $2.2\mu F$ X7R ceramic capacitor is recommended for the DC-DC input. A $1\mu F$ X7R ceramic capacitor is recommended for the V_{AV} pin.

Inductor Selection

Use a 1µH inductor for MAX20472/MAX20471 and MAX20472B. For a ferrite core, the saturation current should be greater than the maximum current limit. For a soft-saturation core, the saturation current can be less than the maximum current limit as long as the inductance at the maximum current limit is greater than 50% of the nominal inductance.

Boost Output Capacitor

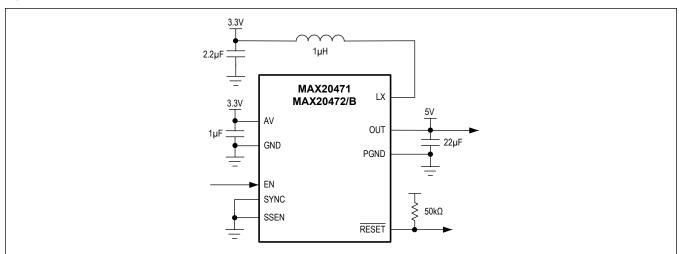
The MAX20471, MAX20472, and MAX20472B are designed to be stable with low-ESR ceramic capacitors. Other capacitor types are not recommended, as the ESR zero can affect stability of the device. The output-capacitor calculations below are guidelines based on nominal conditions. The phase margin must be measured on the final circuit to verify that proper stability is achieved.

$$C_{\text{OUT_MIN}} = \frac{55 \,\mu \,\text{sec}}{V_{\text{OUT}}}$$
$$C_{\text{OUT_NOM}} = \frac{110 \,\mu \,\text{sec}}{V_{\text{OUT}}}$$

PCB Layout Guidelines

When laying out the PCB, keep the DC-DC power components close together and the routes short to minimize loop area. The output capacitor, power inductor, and input capacitor should be placed close to the IC package. The output capacitor experiences the greatest amount of ripple current, and should be placed closest to the IC. The higher current-carrying traces, such as the input (LX) and OUT, should be wide. Vias should connect the exposed pad of the ICs to provide optimal ground and thermal dissipation connections. A large ground plane should be placed directly below the power traces.

Typical Application Circuit



Ordering Information

PART NUMBER	TEMP RANGE	PIN- PACKAGE	V _{OUT} (V)	t _{HOLD} (μs)	INPUT CURRENT LIMIT (A)	CHARGE- MODE CURRENT (±30%) (A)	C _{OUT} OPTION
MAX20471ATCA/ V+	-40°C to +125°C	12 TDFN- EP*	5	500	1.8	1.7	Standard
MAX20471ATCB/ V+	-40°C to +125°C	12 TDFN- EP*	5.15	500	1.8	1.7	Standard
MAX20471ATCC/ V+*	-40°C to +125°C	12 TDFN- EP*	5	500	1.8	1.7	Low
MAX20471ATCB/ VY+	-40°C to +125°C	12 SWTDFN- EP*	5.15	500	1.8	1.7	Standard
MAX20471ATCA/ VY+	-40°C to +125°C	12 SWTDFN- EP*	5	500	1.8	1.7	Standard
MAX20471ASAA/ V+	-40°C to +125°C	8 SOIC	5	500	1.8	1.7	Standard
MAX20472ATCA/ V+	-40°C to +125°C	12 TDFN- EP*	5	500	4.2	1.7	Standard
MAX20472ATCB/ V+	-40°C to +125°C	12 TDFN- EP*	5.15	500	4.2	1.7	Standard
MAX20472ATCC/ V+	-40°C to +125°C	12 TDFN- EP*	3.85	500	4.2	1.7	Standard
MAX20472ATCA/ VY+	-40°C to +125°C	12 SWTDFN- EP*	5	500	4.2	1.7	Standard
MAX20472BATCC/ V+	-40°C to +125°C	12 TDFN- EP*	3.85	500	4.2	1.7	Standard
MAX20472ATCE/ V+	-40°C to +125°C	12 TDFN- EP*	5	14800	4.2	1.7	Standard
MAX20471CATCA/ V+	-40°C to +125°C	12 TDFN- EP*	5	500	1.8	0.63	Standard
MAX20471CATCB/ V+*	-40°C to +125°C	12 TDFN- EP*	5.15	500	1.8	0.63	Standard
MAX20472CATCA/ V+	-40°C to +125°C	12 TDFN- EP*	5	500	4.2	0.63	Standard
MAX20472CATCB/ V+*	-40°C to +125°C	12 TDFN- EP*	5.15	500	4.2	0.63	Standard
MAX20472DATCC/ V+	-40°C to +125°C	12 TDFN- EP*	3.85	500	4.2	0.63	Standard

Note: For variants with different options, contact factory.

N Denotes an automotive-qualified part.

^{*} Potential future part.

Y Denotes side-wettable.

⁺ Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

^{*}EP = Exposed pad.

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Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION		
0	9/17	Initial Release	_	
1	1/18	Changed part in Ordering Information table from MAX20471ASA/V+** to MAX20471ASAA/V+** and removed future product status from MAX20472ATCA/V*	9	
2	5/18	Updated Internal Oscillator section and added Boost Converter Short Protection, Startup into Short, and Short or Overload after Soft-Start sections	7, 8	
3	6/18	Added MAX20472ATCB/V+** (future product) to Ordering Information table.	10	
4	9/18	Removed all references to MAX20473 and 2A convertor operation; updated Pin Configuration; updated Functional Diagram; updated Inductor Selection and Output Capacitor sections; updated Typical Application Circuit; removed MAX20473ATCA/V+** and future-part designation for MAX20471ATCB/V+ from the Ordering Information table	1–11	
5	11/18	Removed future-part designation for MAX20472ATCB/V+ from the Ordering Information table	11	
6	12/18	Updated Package Information table	2	
7	3/19	Added information for SWTDFN package to Benefits and Features, Absolute Maximum Ratings, Package Information, Pin Configurations, and Ordering Information; added MAX20472ATCC/V+** to Ordering Information	1, 2, 6, 11	
8	6/19	Removed future-part designation from MAX20471ASAA/V+ in the Ordering Information table	11	
9	8/19	Added notes to Ordering Information table	11	
9.1		Corrected Revision Date for Rev 9 in Revision History	11	
10	6/20	Added MAX20472B	1–14	
11	8/20	Updated Package Information, Ordering Information	3, 14	
12	9/20	Updated Benefits and Features, Absolute Maximum Ratings, Electrical Characteristics, Pin Description, Detailed Description, and Applications Information; removed future-product notation from MAX20471ATCA/VY+T in Ordering Information	1, 3, 4, 5, 7, 8, 10, 12, 13	
13	9/21	Updated Electrical Characteristics, Detailed Description, and Ordering Information	4, 5, 10, 13	
14	7/22	Updated Detailed Description and Ordering Information	11, 12	
15	9/22	Updated Ordering Information	12	
16	12/24	Updated Ordering Information	12	

